



Attorney's Docket No.: 42P13856D

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of:

Rahul N. Manepalli et al.

Application No.: 10/774,155

Filed: February 5, 2004

For: AN UNDERFILLING PROCESS IN
A MOLDED MATRIX ARRAY
PACKAGE USING FLOW FRONT
MODIFYING SOLDER RESIST

Examiner: Dolan, Jennifer M.

Art Unit: 2813

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AND RESPONSE

Dear Examiner:

This is in response to the Office Action mailed March 16, 2005 and the Request for Continued Examination (RCE) under 37 C.F.R. §1.114 filed concurrently herewith.

Applicant respectfully requests the Examiner to enter the following amendments beginning on page 2 and consider the following remarks beginning on page 8 of this paper.

FIRST CLASS CERTIFICATE OF MAILING

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COMMISSIONER FOR PATENTS, P.O. Box 1450, Alexandria, VA 22313-1450

U.S. Patent and Trademark Office, Washington, D.C. 20231 on

June 8, 2006

Date of Deposit

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